

## **IN THE CLAIMS**

CLAIMS 1 – 6 (Canceled)

CLAIM 7 (Previously Presented) A method according to claim 49 wherein said sheet is spaced apart from said surface by a flexible support.

CLAIMS 8 – 9 (Canceled)

CLAIM 10 (Previously Presented) A method according to claim 7 wherein said sheet and said flexible support forms a space containing said plurality of elongated electrical conductors.

CLAIMS 11 – 40 (Canceled)

CLAIM 41 (Original) A method comprising:

providing a substrate having a surface;

forming a plurality of elongated electrical conductors extending away from said surface; each of said elongated electrical conductors having a first end affixed to said surface and a second end projecting away from said surface;

there being a plurality of said second ends;

providing a means for maintaining said plurality of said second ends in substantially fixed positions with respect to each other.

CLAIM 42 (Previously Presented) A method according to claim 41 wherein said means for maintaining is a sheet formed from a material selected from the group consisting of Invar, Cu/Invar/Cu, molybdenum and polyimides.

**CLAIM 43 (Previously Presented)** A method according to claim 41 wherein said means for maintaining is a sheet formed from a material selected from the group consisting of a metal, a polymer, a semiconductor and dielectric.

**CLAIMS 44 – 48 (Canceled)**

**CLAIM 49 (Previously Presented)** A method according to claim 41 wherein said means for maintaining comprises a sheet of material comprising openings comprising a large region and a small region.

**CLAIM 50 (Canceled)**

**CLAIM 51 (Previously Presented)** A method according to claim 41 wherein said means for maintaining comprises openings comprising a large region and a small region, said compliant elongated electrical conductors are first inserted through said large region and then moved to said small region.

**CLAIMS 52 – 57 (Canceled)**

**CLAIM 58 (Previously Presented)** A method according to claim 41 wherein said means for maintaining is a sheet of material comprising a plurality of openings through which said second ends project.

**CLAIM 59 (Previously Presented)** A method according to claim 41 wherein said means for maintaining comprises at least one sheet of material comprising a plurality of openings through which said second ends project.

**CLAIM 60 (Previously Presented)** A structure according to claim 59 wherein of said at least one sheet is a sheet of electrically conductive material which has a top surface and a

bottom surface and said openings have a sidewall, a dielectric material coats said top surface and said bottom surface and said sidewall.

CLAIM 61 – 63 (Canceled)

CLAIM 64 (New) The structure according to claim 51 wherein each of said elongated electrical conductors projects through one of said openings in said sheet of material.

CLAIM 65 (New) The structure according to claim 58 wherein each of said elongated electrical conductors projects through one of said plurality of openings in said sheet of material.

CLAIM 66 (New) The structure according to claim 59 wherein each of said elongated electrical conductors projects through one of said plurality of openings in said sheet of material.

CLAIM 67 (New) The structure according to claim 41 wherein said means for maintaining comprises openings which are larger in size than said elongated electrical conductor and wherein each of said elongated electrical conductors projects through one of said openings in said sheet of material.

CLAIM 68 (New) The structure according to claim 58 wherein each of said plurality of openings is larger in size than said elongated electrical conductor.

## REMARKS

Reconsideration is respectfully requested in view of any changes to the claims and the remarks herein. Please contact the undersigned to conduct a telephone interview in accordance with MPEP 713.01 to resolve any remaining requirements and/or issues prior to sending another Office Action. Relevant portions of MPEP 713.01 are included on the signature page of this amendment. This response is in supplement to applicants' response submitted on May 31, 2007.

Claims 64-68 are added herein. Support for these added claims is found throughout applicants' specification in particular in applicants' Fig. 28 and the description corresponding thereto and as explained in applicants' response of May 31, 2007.

In view of the remarks herein the Examiner is respectfully requested to withdraw the rejection of claims 54-68 under 35 USC 102(e) as anticipated by Okubo.

In view of the changes to the claims and the remarks herein, the Examiner is respectfully requested to reconsider the above-identified application. If the Examiner wishes to discuss the application further, or if additional information would be required, the undersigned will cooperate fully to assist in the prosecution of this application.

Please charge any fee necessary to enter this paper and any previous paper to deposit account 09-0468.

If the above-identified Examiner's Action is a final Action, and if the above-identified application will be abandoned without further action by applicants, applicants file a Notice of Appeal to the Board of Appeals and Interferences appealing the final rejection of the claims in the above-identified Examiner's Action. Please charge deposit account 09-0468 any fee necessary to enter such Notice of Appeal.

In the event that this amendment does not result in allowance of all such claims, the undersigned attorney respectfully requests a telephone interview at the Examiner's earliest convenience.

MPEP 713.01 states in part as follows:

Where the response to a first complete action includes a request for an interview or a telephone consultation to be initiated by the examiner, ... the examiner, as soon as he or she has considered the effect of the response, should grant such request if it appears that the interview or consultation would result in expediting the case to a final action.

Respectfully submitted,

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